	74AC11074 DUAL POSITIVE-EDGE-TRIGGERED D-TYPE FLIP-FLOP WITH CLEAR AND PRESET SCAS499A – DECEMBER 1986 – REVISED APRIL 1996
 Center-Pin V_{CC} and GND Configurati Minimize High-Speed Switching Nois 	
 EPIC[™] (Enhanced-Performance Impl CMOS) 1-µm Process 	lanted 1PRE 1 14 1CLK 1Q 2 13 1D
 500-mA Typical Latch-Up Immunity a 125°C 	$\begin{array}{cccccccccccccccccccccccccccccccccccc$
 Package Options Include Plastic Small-Outline (D) and Thin Shrink Small-Outline (PW) Packages, and Standard Plastic 300-mil DIPs (N) 	2Q [5 10] 2CLR 2Q [6 9] 2D 2PRE [7 8] 2CLK

description

This device contains two independent positive-edge-triggered D-type flip-flops. A low level at the preset (\overline{PRE}) or clear (\overline{CLR}) input sets or resets the outputs regardless of the levels of the other inputs. When \overline{PRE} and \overline{CLR} are inactive (high), data at the data (D) input that meets the setup-time requirements are transferred to the outputs on the low-to-high transition of the clock (CLK) pulse. Clock triggering occurs at a voltage level and is not directly related to the rise time of the clock pulse. Following the hold-time interval, data at the D input may be changed without affecting the levels at the outputs.

The 74AC11074 is characterized for operation from -40°C to 85°C.

	F	UNCTIO	N TABL	E	
	INP	UTS		OUT	PUT
PRE	CLR	CLK	D	Q	Q
L	Н	Х	Х	Н	L
н	L	Х	Х	L	Н
L	L	Х	Х	н†	H‡
н	Н	î	Н	н	L
н	Н	î	L	L	Н
Н	Н	L	Х	Q ₀	\overline{Q}_0

[†] This configuration is nonstable; that is, it does not persist when PRE or CLR returns to its inactive (high) level.



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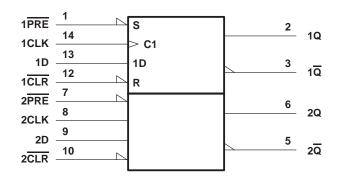


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logic symbol[†]



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[‡]

Supply voltage range, V _{CC}	
Input voltage range, V _I (see Note 1)	–0.5 V to V _{CC} + 0.5 V
Output voltage range, V _O (see Note 1)	–0.5 V to V _{CC} + 0.5 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$)	±20 mA
Output clamp current, I_{OK} (V _O < 0 or V _O > V _{CC})	±50 mA
Continuous output current, $I_O (V_O = 0 \text{ to } V_{CC})$	±50 mA
Continuous current through V _{CC} or GND	±100 mA
Maximum power dissipation at $T_A = 55^{\circ}C$ (in still air) (see Note 2):	D package 1.25 W
	N package 1.1 W
	PW package 0.5 W
Storage temperature range, T _{stg}	–65°C to 150°C

[‡] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils, except for the N package, which has a trace length of zero.



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recommended operating conditions

			MIN	NOM	MAX	UNIT
VCC	Supply voltage		3	5	5.5	V
		$V_{CC} = 3 V$	2.1			
VIH	High-level input voltage	$V_{CC} = 4.5 V$	3.15			V
		$V_{CC} = 5.5 V$	3.85			
		$V_{CC} = 3 V$			0.9	
VIL	Low-level input voltage $V_{CC} = 4.5 V$				1.35	V
		V _{CC} = 5.5 V			1.65	
\vee_{I}	Input voltage	0		VCC	V	
VO	Output voltage		0		VCC	V
		$V_{CC} = 3 V$			-4	
ЮН	High-level output current	$V_{CC} = 4.5 V$			-24	mA
		V _{CC} = 5.5 V			-24	
		V _{CC} = 3 V			12	
IOL	Low-level output current	V _{CC} = 4.5 V			24	mA
		V _{CC} = 5.5 V			24	
$\Delta t / \Delta v$	Input transition rise or fall rate		0		10	ns/V
TA	Operating free-air temperature	-40		85	°C	

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DADAMETED	TEST CONDITIONS	N	T,	4 = 25°C	;	MIN		LINUT
PARAMETER	TEST CONDITIONS	v _{cc}	MIN	TYP	MAX	MIN	MAX	UNIT
		3 V	2.9			2.9		
	I _{OH} = -50 μA	4.5 V	4.4			4.4		
		5.5 V	5.4			5.4		
VOH	$I_{OH} = -4 \text{ mA}$	3 V	2.58			2.48		V
		4.5 V	3.94			3.8		
	$I_{OH} = -24 \text{ mA}$	5.5 V	4.94			4.8		
	$I_{OH} = -75 \text{ mA}^{\dagger}$	5.5 V				3.85		
		3 V			0.1		0.1	
	l _{OL} = 50 μA	4.5 V			0.1		0.1	
		5.5 V			0.1		0.1	
VOL	I _{OL} = 12 mA	3 V			0.36		0.44	V
		4.5 V			0.36		0.44	
	I _{OL} = 24 mA	5.5 V			0.36		0.44	
	$I_{OL} = 75 \text{ mA}^{\dagger}$	5.5 V					1.65	
lj	$V_I = V_{CC}$ or GND	5.5 V			±0.1		±1	μΑ
ICC	$V_{I} = V_{CC} \text{ or } GND, \qquad I_{O} = 0$	5.5 V			4		40	μΑ
Ci	$V_{I} = V_{CC} \text{ or } GND$	5 V		3.5				pF

[†] Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.



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timing requirements over recommended operating free-air temperature range,

 $V_{CC} = 3.3 V \pm 0.3 V$ (see Figure 1)

			T _A = 2	25°C		MAX		
			MIN	MAX	MIN	MAX	UNIT	
fclock	Clock frequency		0	100	0	100	MHz	
	Dulas duration	PRE or CLR low	4		4			
tw	Pulse duration	CLK low or high	5		5		ns	
		Data high or low	5		5			
^t su	Setup time before CLK [↑]	PRE or CLR inactive	1		1		ns	
th	Hold time after CLK↑	0		0		ns		

timing requirements over recommended operating free-air temperature range, $V_{CC} = 5 V \pm 0.5 V$ (see Figure 1)

			T _A = 2	25°C	MIN			
			MIN	MAX	WIIN	MAX	UNIT	
fclock	Clock frequency		0	125	0	125	MHz	
	Delas duration	PRE or CLR low	4		4			
tw	Pulse duration	CLK low or CLK high	4		4		ns	
		Data high or low	3.5		3.5			
^t su	Setup time before CLK↑	PRE or CLR inactive	1		1		ns	
t _h	Hold time after CLK↑	0		0		ns		

switching characteristics over recommended operating free-air temperature range, V_{CC} = 3.3 V ± 0.3 V (unless otherwise noted) (see Figure 1)

DADAMETED	FROM	ТО	Т	₄ = 25°C	;			
PARAMETER	(INPUT)	(OUTPUT)	MIN	TYP	MAX	MIN	MAX	UNIT
fmax			100	125		100		MHz
^t PLH				5.8	9.3	1.5	10	
^t PHL	PRE or CLR	Q or Q	1.5	6.5	11.4	1.5	12.2	ns
^t PLH		0	1.5	7.7	10.5	1.5	11.3	20
^t PHL	CLK	Q or Q	1.5	7.3	9.7	1.5	10.6	ns

switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	ТО	Т	₄ = 25°C	;			
	(INPUT)	(OUTPUT)	MIN	TYP	MAX	MIN	MAX	UNIT
fmax			125	150		125		MHz
^t PLH	PRE or CLR	0	1.5	4.2	6.6	1.5	7.1	
^t PHL	PRE OF GLR	Q or Q	1.5	4.7	8.2	1.5	9	ns
^t PLH		0	1.5	5.4	7.5	1.5	8.2	
^t PHL	CLK	Q or Q	1.5	5	6.9	1.5	7.5	ns

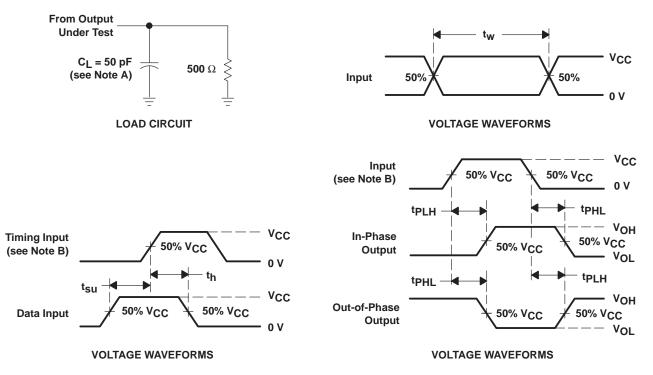
operating characteristics, V_{CC} = 5 V, T_A = 25°C

	PARAMETER	TEST CON	NDITIONS	TYP	UNIT
C _{pd}	Power dissipation capacitance	C _L = 50 pF,	f = 1 MHz	30	pF



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PARAMETER MEASUREMENT INFORMATION

NOTES: A. C_L includes probe and jig capacitance.

B. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_O = 50 Ω , t_r = 3 ns, t_f = 3 ns. C. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms



4-Jun-2007

PACKAGING INFORMATION

JMENTS

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Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Packag Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
74AC11074D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74AC11074DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74AC11074DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74AC11074DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74AC11074DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74AC11074DRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74AC11074N	ACTIVE	PDIP	Ν	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
74AC11074NE4	ACTIVE	PDIP	Ν	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
74AC11074NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74AC11074NSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74AC11074NSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74AC11074PWLE	OBSOLETE	TSSOP	PW	14		TBD	Call TI	Call TI
74AC11074PWR	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74AC11074PWRE4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74AC11074PWRG4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details. TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.



PACKAGE OPTION ADDENDUM

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TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*A	I dimensions are nominal												
	Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
	74AC11074DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
	74AC11074NSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
	74AC11074PWR	TSSOP	PW	14	2000	330.0	12.4	7.0	5.6	1.6	8.0	12.0	Q1



PACKAGE MATERIALS INFORMATION

11-Mar-2008



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
74AC11074DR	SOIC	D	14	2500	346.0	346.0	33.0
74AC11074NSR	SO	NS	14	2000	346.0	346.0	33.0
74AC11074PWR	TSSOP	PW	14	2000	346.0	346.0	29.0

MECHANICAL DATA

MTSS001C - JANUARY 1995 - REVISED FEBRUARY 1999

PW (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
- D. Falls within JEDEC MO-153



MECHANICAL DATA

PLASTIC SMALL-OUTLINE PACKAGE

0,51 0,35 ⊕0,25⊛ 1,27 8 14 0,15 NOM 5,60 8,20 5,00 7,40 \bigcirc Gage Plane ₽ 0,25 7 1 1,05 0,55 0°-10° Δ 0,15 0,05 Seating Plane — 2,00 MAX 0,10PINS ** 14 16 20 24 DIM 10,50 10,50 12,90 15,30 A MAX A MIN 9,90 9,90 12,30 14,70 4040062/C 03/03

NOTES: A. All linear dimensions are in millimeters.

NS (R-PDSO-G**)

14-PINS SHOWN

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



D (R-PDSO-G14)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.

Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.

E. Reference JEDEC MS-012 variation AB.



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- \triangle The 20 pin end lead shoulder width is a vendor option, either half or full width.



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